

MOS FIELD EFFECT TRANSISTOR 2SK3668

SWITCHING N-CHANNEL POWER MOS FET

DESCRIPTION

The 2SK3668 is N-channel DMOS FET device that features a low on-state resistance, low charge and excellent switching characteristics, designed for high voltage applications such as high intensity discharge lamp drive.

FEATURES

- Low gate charge
 Qg = 26 nC TYP. (VDD = 320 V, Vgs = 10 V, ID = 10 A)
- Gate voltage rating: ±30 V
- Low on-state resistance $R_{DS(on)} = 0.55 \Omega$ MAX. (Vgs = 10 V, Ip = 5.0 A)
- Surface mount package available

ORDERING INFORMATION

PART NUMBER	PACKAGE		
2SK3668-ZK	TO-263 (MP-25ZK)		

(TO-263)



ABSOLUTE MAXIMUM RATINGS (TA = 25°C)

Drain to Source Voltage (Vgs = 0 V)	VDSS	400	V
Gate to Source Voltage (Vps = 0 V)	Vgss	±30	V
Drain Current (DC) (Tc = 25°C)	I _{D(DC)}	±10	Α
Drain Current (pulse) Note1	D(pulse)	±34	Α
Total Power Dissipation (T _A = 25°C)	P _{T1}	1.5	W
Total Power Dissipation (Tc = 25°C)	P _{T2}	100	W
Channel Temperature	Tch	150	°C
Storage Temperature	Tstg	-55 to +150	°C
Single Avalanche Current Note2	las	10	Α
Single Avalanche Energy Note2	Eas	8	mJ

Notes 1. PW \leq 10 μ s, Duty Cycle \leq 1%

2. Starting Tch = 25°C, VDD = 150 V, Rg = 25 Ω , Vgs = 20 \rightarrow 0 V, L = 100 μ H

THERMAL RESISTANCE

Channel to Case Thermal Resistance	Rth(ch-C)	1.25	°C/W
Channel to Ambient Thermal Resistane	Rth(ch-A)	83.3	°C/W

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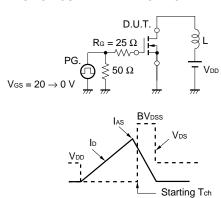


ELECTRICAL CHARACTERISTICS (TA = 25°C)

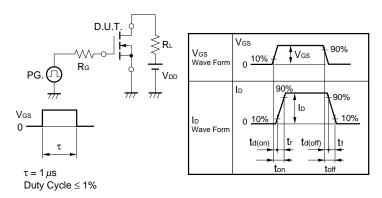
	CHARACTERISTICS	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNIT
	Zero Gate Voltage Drain Current	Ioss	V _{DS} = 400 V, V _{GS} = 0 V			100	μΑ
	Gate Leakage Current	Igss	$V_{GS} = \pm 30 \text{ V}, V_{DS} = 0 \text{ V}$			±100	nA
	Gate Cut-off Voltage	$V_{GS(off)}$	V _{DS} = 10 V, I _D = 1.0 mA	2.5		3.5	V
*	Forward Transfer Admittance Note	yfs	V _{DS} = 10 V, I _D = 5.0 A	3.0	5.6		S
k	Drain to Source On-state Resistance Note	R _{DS(on)}	Vgs = 10 V, ID = 5.0 A		0.40	0.55	Ω
	Input Capacitance	Ciss	Vps = 10 V		1320		pF
	Output Capacitance	Coss	Vgs = 0 V		230		pF
	Reverse Transfer Capacitance	Crss	f = 1.0 MHz		13		pF
U.	com Turn-on Delay Time	td(on)	VDD = 150 V, ID = 5.0 A		18		ns
	Rise Time	t r	Vgs = 10 V		8		ns
	Turn-off Delay Time	td(off)	R _G = 10 Ω		44		ns
	Fall Time	t f			4		ns
	Total Gate Charge	Q _G	VDD = 320 V		26		nC
	Gate to Source Charge	Qgs	Vgs = 10 V		7		nC
	Gate to Drain Charge	Q _{GD}	ID = 10 A		11		nC
	Body Diode Forward Voltage Note	V _{F(S-D)}	IF = 10 A, VGS = 0 V		0.90		V
	Reverse Recovery Time	trr	IF = 10 A, VGS = 0 V		350		ns
	Reverse Recovery Charge	Qrr	di/dt = 100 A/μs		2.7		μC

Note Pulsed: PW \leq 800 μ s, Duty Cycle \leq 2%

TEST CIRCUIT 1 AVALANCHE CAPABILITY

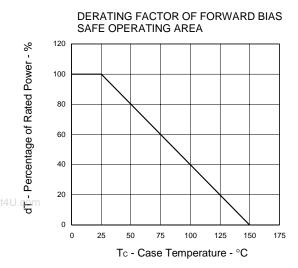


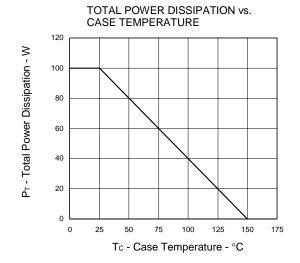
TEST CIRCUIT 2 SWITCHING TIME



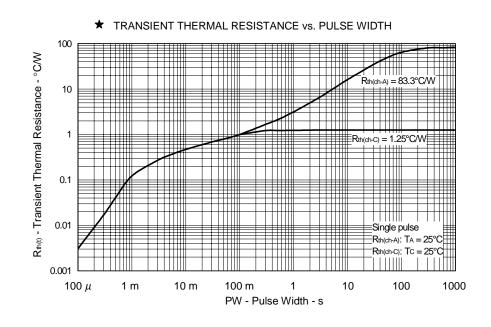
TEST CIRCUIT 3 GATE CHARGE

TYPICAL CHARACTERISTICS (TA = 25°C)



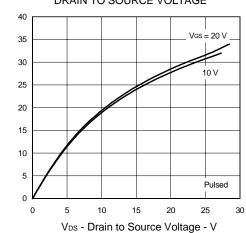


FORWARD BIAS SAFE OPERATING AREA 100 PW = 1 ms _10 ms Ip - Drain Current - A 100 ms 10 on) Limited шш (at Vgs = 10 V) Tc = 25°C Single puls 0.01 0.1 1000 V_{DS} - Drain to Source Voltage - V

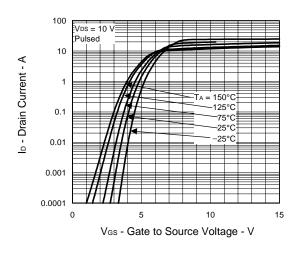


Ib - Drain Current - A

DRAIN CURRENT vs. DRAIN TO SOURCE VOLTAGE

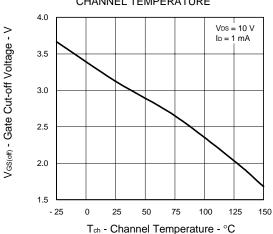


FORWARD TRANSFER CHARACTERISTICS

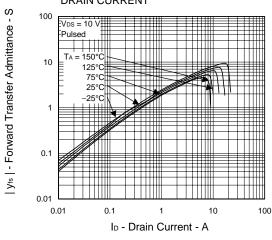


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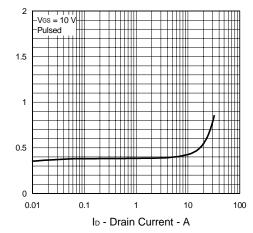
GATE CUT-OFF VOLTAGE vs. CHANNEL TEMPERATURE



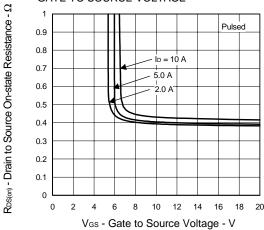
FORWARD TRANSFER ADMITTANCE vs. DRAIN CURRENT



DRAIN TO SOURCE ON-STATE RESISTANCE vs. DRAIN CURRENT



DRAIN TO SOURCE ON-STATE RESISTANCE vs. GATE TO SOURCE VOLTAGE

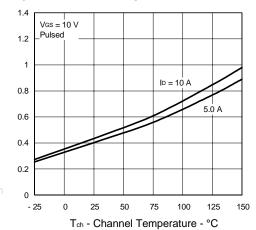


 $\mathsf{R}_{\mathsf{DS}(\mathsf{on})}$ - Drain to Source On-state Resistance - Ω

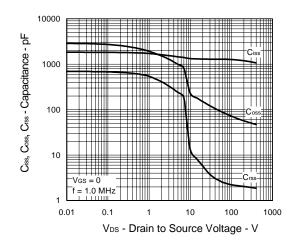
 $\mathsf{R}_{\mathsf{DS}(\overline{\omega})}$ - Drain to Source On-state Resistance - Ω

Ves - Gate to Source Voltage - V

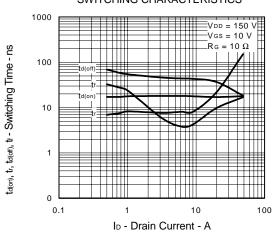
DRAIN TO SOURCE ON-STATE RESISTANCE vs. CHANNEL TEMPERATURE



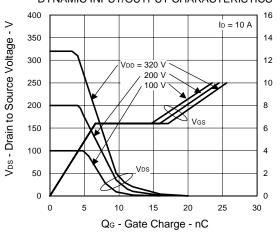
CAPACITANCE vs. DRAIN TO SOURCE VOLTAGE



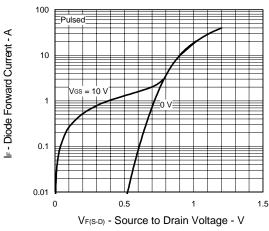
SWITCHING CHARACTERISTICS



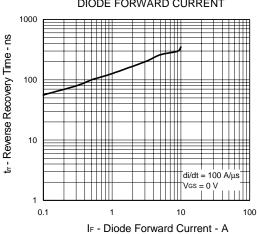
DYNAMIC INPUT/OUTPUT CHARACTERISTICS



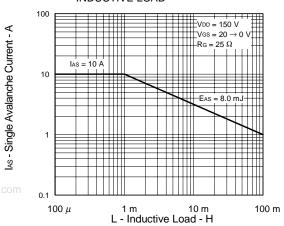
SOURCE TO DRAIN DIODE FORWARD VOLTAGE



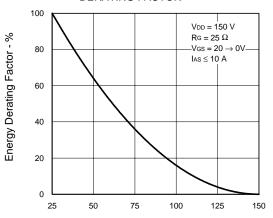
REVERSE RECOVERY TIME vs. DIODE FORWARD CURRENT



★ SINGLE AVALANCHE CURRENT vs. INDUCTIVE LOAD



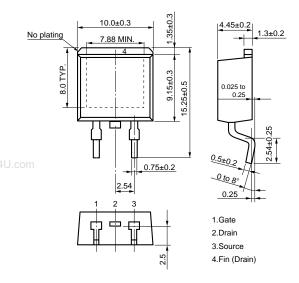
SINGLE AVALANCHE ENERGY DERATING FACTOR



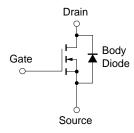
Starting Tch - Starting Channel Temperature - °C

PACKAGE DRAWING (Unit: mm)

TO-263 (MP-25ZK)



EQUIVALENT CIRCUIT



Remark Strong electric field, when exposed to this device, can cause destruction of the gate oxide and ultimately degrade the device operation. Steps must be taken to stop generation of static electricity as much as possible, and quickly dissipate it once, when it has occurred.

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